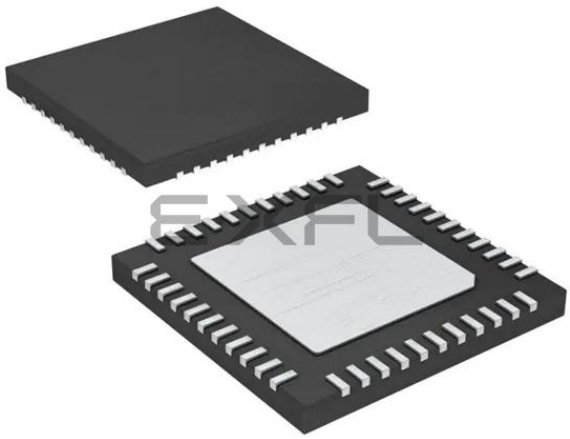


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	36
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 35x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf18876-e-ml

PIN ALLOCATION TABLES

TABLE 2: 28-PIN ALLOCATION TABLE (PIC16(L)F18856)

I/O	28-Pin SPDIP/SOIC/SSOP	28-Pin (U)QFN	ADC	Voltage Reference	DAC	Comparators	Zero-Cross Detect	MSSP (SPI/I2C)	EUSART	DSM	Timers/SMT	CCP and PWM	CWG	CLC	NCO	Clock Reference (CLKR)	Interrupt-on-Change	Basic
RA0	2	27	ANA0	—	—	C1IN0- C2IN0-	—	—	—	—	—	—	—	CLCIN0(1)	—	—	IOCA0	—
RA1	3	28	ANA1	—	—	C1IN1- C2IN1-	—	—	—	—	—	—	—	CLCIN1(1)	—	—	IOCA1	—
RA2	4	1	ANA2	VREF-	DAC1OUT1	C1IN0+ C2IN0+	—	—	—	—	—	—	—	—	—	—	IOCA2	—
RA3	5	2	ANA3	VREF+	—	C1IN1+	—	—	—	MDCARL(1)	—	—	—	—	—	—	IOCA3	—
RA4	6	3	ANA4	—	—	—	—	—	—	MDCARH(1)	T0CKI(1)	CCP5(1)	—	—	—	—	IOCA4	—
RA5	7	4	ANA5	—	—	—	—	SS1(1)	—	MDSRC(1)	—	—	—	—	—	—	IOCA5	—
RA6	10	7	ANA6	—	—	—	—	—	—	—	—	—	—	—	—	—	IOCA6	OSC2 CLKOUT
RA7	9	6	ANA7	—	—	—	—	—	—	—	—	—	—	—	—	—	IOCA7	OSC1 CLKIN
RB0	21	18	ANB0	—	—	C2IN1+	ZCD	SS2(1)	—	—	—	CCP4(1)	CWG1IN(1)	—	—	—	INT(1) IOCB0	—
RB1	22	19	ANB1	—	—	C1IN3- C2IN3-	—	SCL2(3,4) SCK2(1)	—	—	—	—	CWG2IN(1)	—	—	—	IOCB1	—
RB2	23	20	ANB2	—	—	—	—	SDA2(3,4) SDI2(1)	—	—	—	—	CWG3IN(1)	—	—	—	IOCB2	—
RB3	24	21	ANB3	—	—	C1IN2- C2IN2-	—	—	—	—	—	—	—	—	—	—	IOCB3	—
RB4	25	22	ANB4 ADCACT(1)	—	—	—	—	—	—	—	T5G(1) SMTWIN2(1)	—	—	—	—	—	IOCB4	—

Note 1: This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTX pins. Refer to Table 13-1 for details on which port pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTX pin options as described in Table 13-3.

3: This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.

4: These pins are configured for I^2C logic levels.; The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I^2C specific or SMbus input buffer thresholds.

2.0 ENHANCED MID-RANGE CPU

This family of devices contains an enhanced mid-range 8-bit CPU core. The CPU has 49 instructions. Interrupt capability includes automatic context saving. The hardware stack is 16-levels deep and has Overflow and Underflow Reset capability. Direct, Indirect, and Relative Addressing modes are available. Two File Select Registers (FSRs) provide the ability to read program and data memory.

- Automatic Interrupt Context Saving
- 16-level Stack with Overflow and Underflow
- File Select Registers
- Instruction Set

FIGURE 2-1: CORE BLOCK DIAGRAM

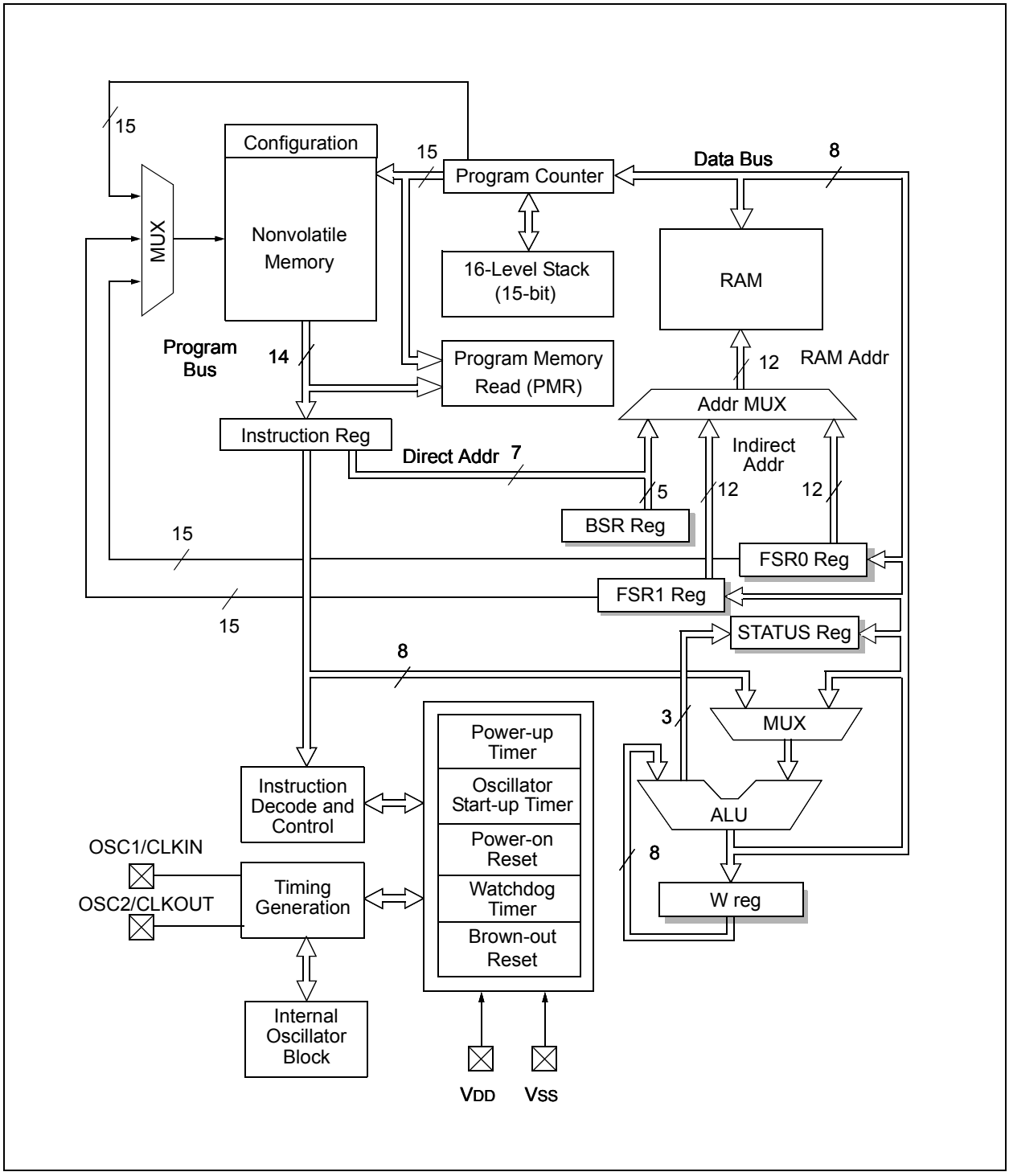


TABLE 3-11: PIC16(L)F18876 MEMORY MAP, BANK 30

	Bank 30
F0Ch	—
F0Dh	—
F0Eh	—
F0Fh	—
F10h	RA0PPS
F11h	RA1PPS
F12h	RA2PPS
F13h	RA3PPS
F14h	RA4PPS
F15h	RA5PPS
F16h	RA6PPS
F17h	RA7PPS
F18h	RB0PPS
F19h	RB1PPS
F1Ah	RB2PPS
F1Bh	RB3PPS
F1Ch	RB4PPS
F1Dh	RB5PPS
F1Eh	RB6PPS
F1Fh	RB7PPS
F20h	RC0PPS
F21h	RC1PPS
F22h	RC2PPS
F23h	RC3PPS
F24h	RC4PPS
F25h	RC5PPS
F26h	RC6PPS
F27h	RC7PPS
F28h — F37h	—
F38h	ANSELA
F39h	WPUA
F3Ah	ODCONA
F3Bh	SLRCONA
F3Ch	INLVLA
F3Dh	IOCAP
F3Eh	IOCAN
F3Fh	IOCAF

	Bank 30
F40h	CCDNA
F41h	CCDPA
F42h	—
F43h	ANSELB
F44h	WPUB
F45h	ODCONB
F46h	SLRCONB
F47h	INLVLB
F48h	IOCBP
F49h	IOCBN
F4Ah	IOCBF
F4Bh	CCDNB
F4Ch	CCDPB
F4Dh	—
F4Eh	ANSELC
F4Fh	WPUC
F50h	ODCONC
F51h	SLRCONC
F52h	INLVLC
F53h	IOCCP
F54h	IOCCN
F55h	IOCCF
F56h	CCDNC
F57h	CCDPC
F58h	—
F59h	ANSELD
F5Ah	WPUD
F5Bh	ODCOND
F5Ch	SLRCOND
F5Dh	INLVLD
F5Eh	—
F5Fh	—
F60h	—
F61h	CCDND
F62h	CCDPD
F63h	—

	Bank 30
F64h	ANSELE
F65h	WPUE
F66h	ODCONE
F67h	SLRCONE
F68h	INLVLE
F69h	IOCEP
F6Ah	IOCEN
F6Bh	IOCEF
F6Ch	CCDNE
F6Dh	CCDPE
F6Eh	—
F6Fh	—

Legend: = Unimplemented data memory locations, read as '0'.

TABLE 3-13: SPECIAL FUNCTION REGISTER SUMMARY BANKS 0-31 (CONTINUED)

Address	Name	PIC16(L)F18856	PIC16(L)F18876	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
Bank 29													
CPU CORE REGISTERS; see Table 3-2 for specifics													
E8Ch	—	—		Unimplemented								—	—
E8Dh	—	—		Unimplemented								—	—
E8Eh	—	—		Unimplemented								—	—
E8Fh	PPSLOCK			—	—	—	—	—	—	—	PPSLOCKED	---- ---0	---- ---0
E90h	INTPPS			—	—	—	—	INTPPS<3:0>				---- 1000	---- uuuu
E91h	T0CKIPPS			—	—	—	—	T0CKIPPS<3:0>				---- 0100	---- uuuu
E92h	T1CKIPPS			—	—	—	T1CKIPPS<4:0>					---1 0000	---u uuuu
E93h	T1GPPS			—	—	—	T1GPPS<4:0>					---0 1101	---u uuuu
E94h	T3CKIPPS			—	—	—	T3CKIPPS<4:0>					---1 0000	---u uuuu
E95h	T3GPPS			—	—	—	T3GPPS<4:0>					---1 0000	---u uuuu
E96h	T5CKIPPS			—	—	—	T5CKIPPS<4:0>					---1 0000	---u uuuu
E97h	T5GPPS			—	—	—	T5GPPS<4:0>					---0 1100	---u uuuu
E98h	—	—		Unimplemented								—	—
E99h	—	—		Unimplemented								—	—
E9Ah	—	—		Unimplemented								—	—
E9Bh	—	—		Unimplemented								—	—
E9Ch	T2AINPPS			—	—	—	T2AINPPS<4:0>					---1 0011	---u uuuu
E9Dh	T4AINPPS			—	—	—	T4AINPPS<4:0>					---1 0101	---u uuuu
E9Eh	T6AINPPS			—	—	—	T6AINPPS<4:0>					---0 1111	---u uuuu
E9Fh	—	—		Unimplemented								—	—
EA0h	—	—		Unimplemented								—	—
EA1h	CCP1PPS			—	—	—	CCP1PPS<4:0>					---1 0010	---u uuuu

Legend: x = unknown, u = unchanged, q =depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations unimplemented, read as '0'.

Note 1: Register present on PIC16F18855/75 devices only.

2: Unimplemented, read as '1'.

5.13 Register Definitions: Power Control

REGISTER 5-2: PCON0: POWER CONTROL REGISTER 0

R/W/HS-0/q	R/W/HS-0/q	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-q/u	R/W/HC-q/u
STKOVF	STKUNF	$\overline{\text{WDTWV}}$	$\overline{\text{RWDT}}$	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$
bit 7							bit 0

Legend:		
HC = Bit is cleared by hardware		HS = Bit is set by hardware
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-m/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **STKOVF:** Stack Overflow Flag bit
1 = A Stack Overflow occurred
0 = A Stack Overflow has not occurred or cleared by firmware

bit 6 **STKUNF:** Stack Underflow Flag bit
1 = A Stack Underflow occurred
0 = A Stack Underflow has not occurred or cleared by firmware

bit 5 **$\overline{\text{WDTWV}}$:** WDT Window Violation Flag bit
1 = A WDT Window Violation Reset has not occurred or set by firmware
0 = A WDT Window Violation Reset has occurred (a CLRWDT instruction was executed either without arming the window or outside the window (cleared by hardware)

bit 4 **$\overline{\text{RWDT}}$:** Watchdog Timer Reset Flag bit
1 = A Watchdog Timer Reset has not occurred or set to '1' by firmware
0 = A Watchdog Timer Reset has occurred (cleared by hardware)

bit 3 **$\overline{\text{RMCLR}}$:** $\overline{\text{MCLR}}$ Reset Flag bit
1 = A $\overline{\text{MCLR}}$ Reset has not occurred or set to '1' by firmware
0 = A $\overline{\text{MCLR}}$ Reset has occurred (cleared by hardware)

bit 2 **$\overline{\text{RI}}$:** RESET Instruction Flag bit
1 = A RESET instruction has not been executed or set to '1' by firmware
0 = A RESET instruction has been executed (cleared by hardware)

bit 1 **$\overline{\text{POR}}$:** Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{\text{BOR}}$:** Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Power-on Reset or Brown-out Reset occurs)

TABLE 5-5: SUMMARY OF REGISTERS ASSOCIATED WITH RESETS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BORCON	SBOREN	—	—	—	—	—	—	BORRDY	104
PCON0	STKOVF	STKUNF	$\overline{\text{WDTWV}}$	$\overline{\text{RWDT}}$	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	109
STATUS	—	—	—	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	38
WDTCON0	—	—	WDTPS<4:0>					SWDTEN	166

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Resets.

6.2 Clock Source Types

Clock sources can be classified as external or internal.

External clock sources rely on external circuitry for the clock source to function. Examples are: oscillator modules (ECH, ECM, ECL mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes).

Internal clock sources are contained within the oscillator module. The internal oscillator block has two internal oscillators and a dedicated Phase Lock Loop (PLL) that are used to generate internal system clock sources. The High-Frequency Internal Oscillator (HFINTOSC) can produce a range from 1 to 32 MHz. The Low-Frequency Internal Oscillator (LFINTOSC) generates a 31 kHz frequency. The external oscillator block can also be used with the PLL. See **Section 6.2.1.4 "4x PLL"** for more details.

The system clock can be selected between external or internal clock sources via the NOSC bits in the OSCCON1 register. See **Section 6.3 "Clock Switching"** for additional information.

6.2.1 EXTERNAL CLOCK SOURCES

An external clock source can be used as the device system clock by performing one of the following actions:

- Program the RSTOSC<2:0> bits in the Configuration Words to select an external clock source that will be used as the default system clock upon a device Reset
- Write the NOSC<2:0> and NDIV<4:0> bits in the OSCCON1 register to switch the system clock source

See **Section 6.3 "Clock Switching"**for more information.

6.2.1.1 EC Mode

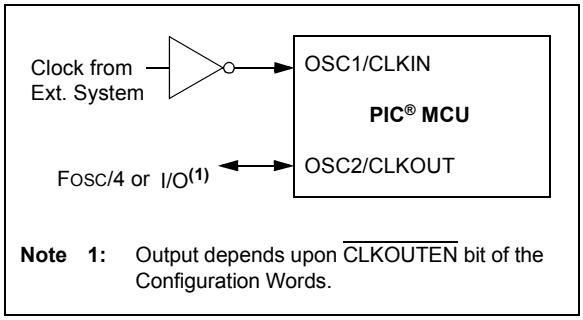
The External Clock (EC) mode allows an externally generated logic level signal to be the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. Figure 6-2 shows the pin connections for EC mode.

EC mode has three power modes to select from through Configuration Words:

- ECH – High power, 4-32 MHz
- ECM – Medium power, 0.1-4 MHz
- ECL – Low power, 0-0.1 MHz

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 6-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Output depends upon $\overline{\text{CLKOUTEN}}$ bit of the Configuration Words.

6.2.1.2 LP, XT, HS Modes

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 6-3). The three modes select a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is designed to drive only 32.768 kHz tuning-fork type crystals (watch crystals).

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

Figure 6-3 and Figure 6-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

REGISTER 7-7: PIE5: PERIPHERAL INTERRUPT ENABLE REGISTER 5

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
CLC4IE	CLC3IE	CLC2IE	CLC1IE	—	TMR5GIE	TMR3GIE	TMR1GIE
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HS = Hardware set

bit 7 **CLC4IE:** CLC4 Interrupt Enable bit
1 = CLC4 interrupt enabled
0 = CLC4 interrupt disabled

bit 6 **CLC3IE:** CLC3 Interrupt Enable bit
1 = CLC3 interrupt enabled
0 = CLC3 interrupt disabled

bit 5 **CLC2IE:** CLC2 Interrupt Enable bit
1 = CLC2 interrupt enabled
0 = CLC2 interrupt disabled

bit 4 **CLC1IE:** CLC1 Interrupt Enable bit
1 = CLC1 interrupt enabled
0 = CLC1 interrupt disabled

bit 3 **Unimplemented:** Read as '0'

bit 2 **TMR5GIE:** Timer5 Gate Interrupt Enable bit
1 = Enables the Timer5 gate acquisition interrupt
0 = Disables the Timer5 gate acquisition interrupt

bit 1 **TMR3GIE:** Timer3 Gate Interrupt Enable bit
1 = Enables the Timer3 gate acquisition interrupt
0 = Disables the Timer3 gate acquisition interrupt

bit 0 **TMR1GIE:** Timer1 Gate Interrupt Enable bit
1 = Enables the Timer1 gate acquisition interrupt
0 = Disables the Timer1 gate acquisition interrupt

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt controlled by registers PIE1-PIE8.

10.4.8 WRITE VERIFY

It is considered good programming practice to verify that program memory writes agree with the intended value. Since program memory is stored as a full page then the stored program memory contents are compared with the intended data stored in RAM after the last write is complete.

FIGURE 10-8: FLASH PROGRAM MEMORY VERIFY FLOWCHART

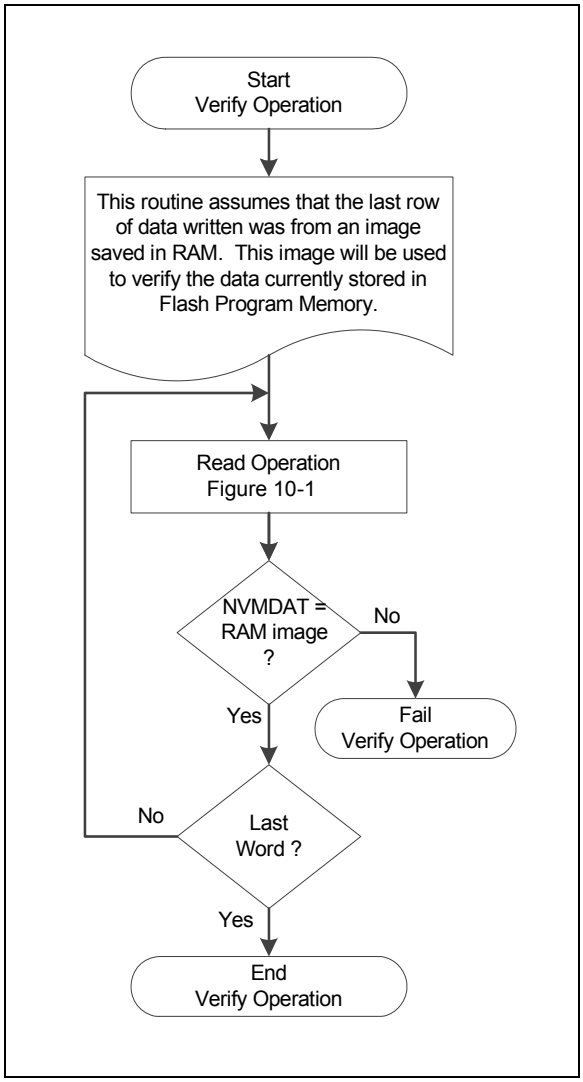


FIGURE 20-13: SHUTDOWN FUNCTIONALITY, AUTO-RESTART DISABLED (REN = 0, LSAC = 01, LSBD = 01)

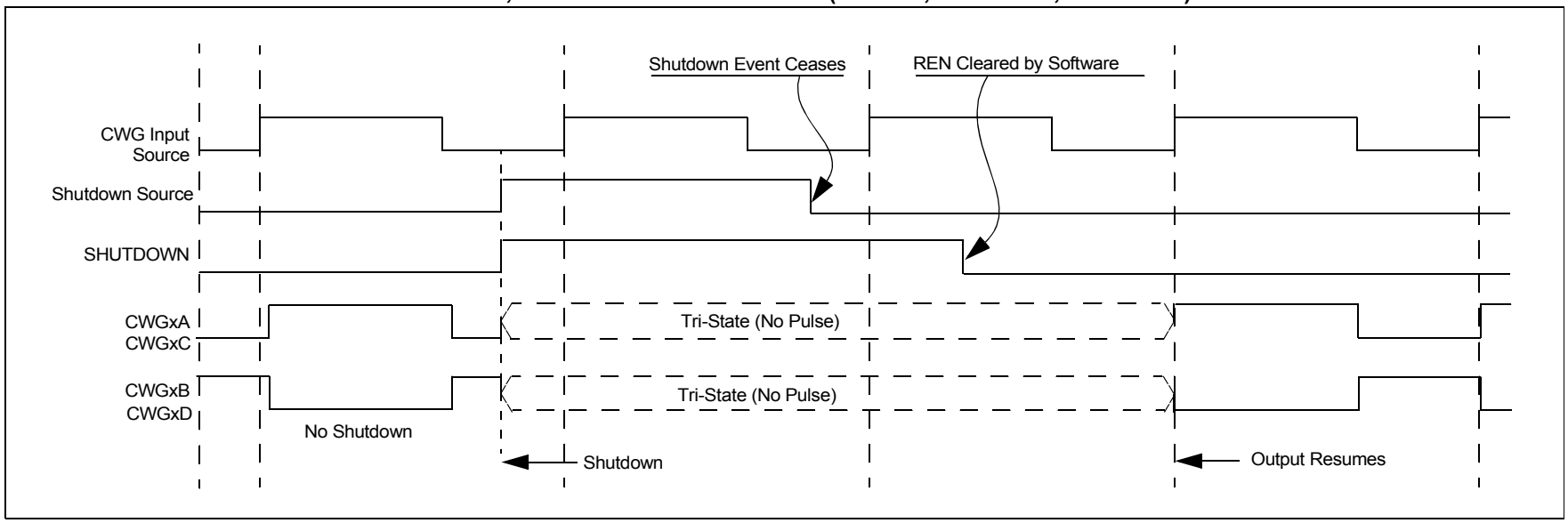


FIGURE 20-14: SHUTDOWN FUNCTIONALITY, AUTO-RESTART ENABLED (REN = 1, LSAC = 01, LSBD = 01)

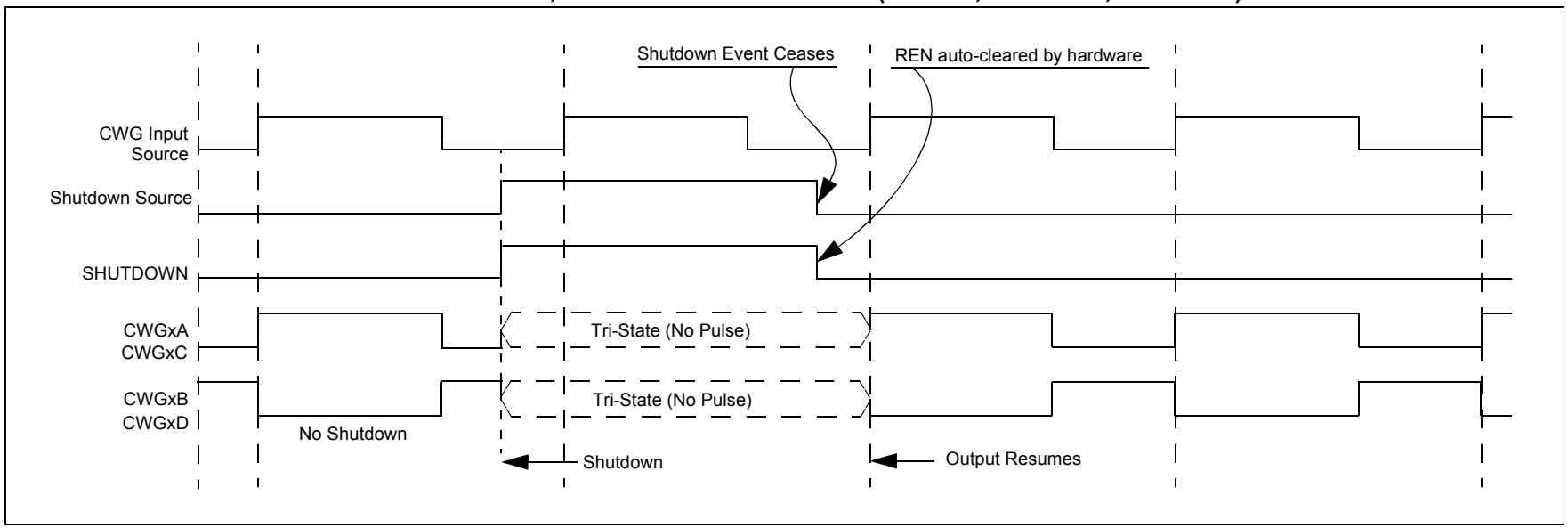
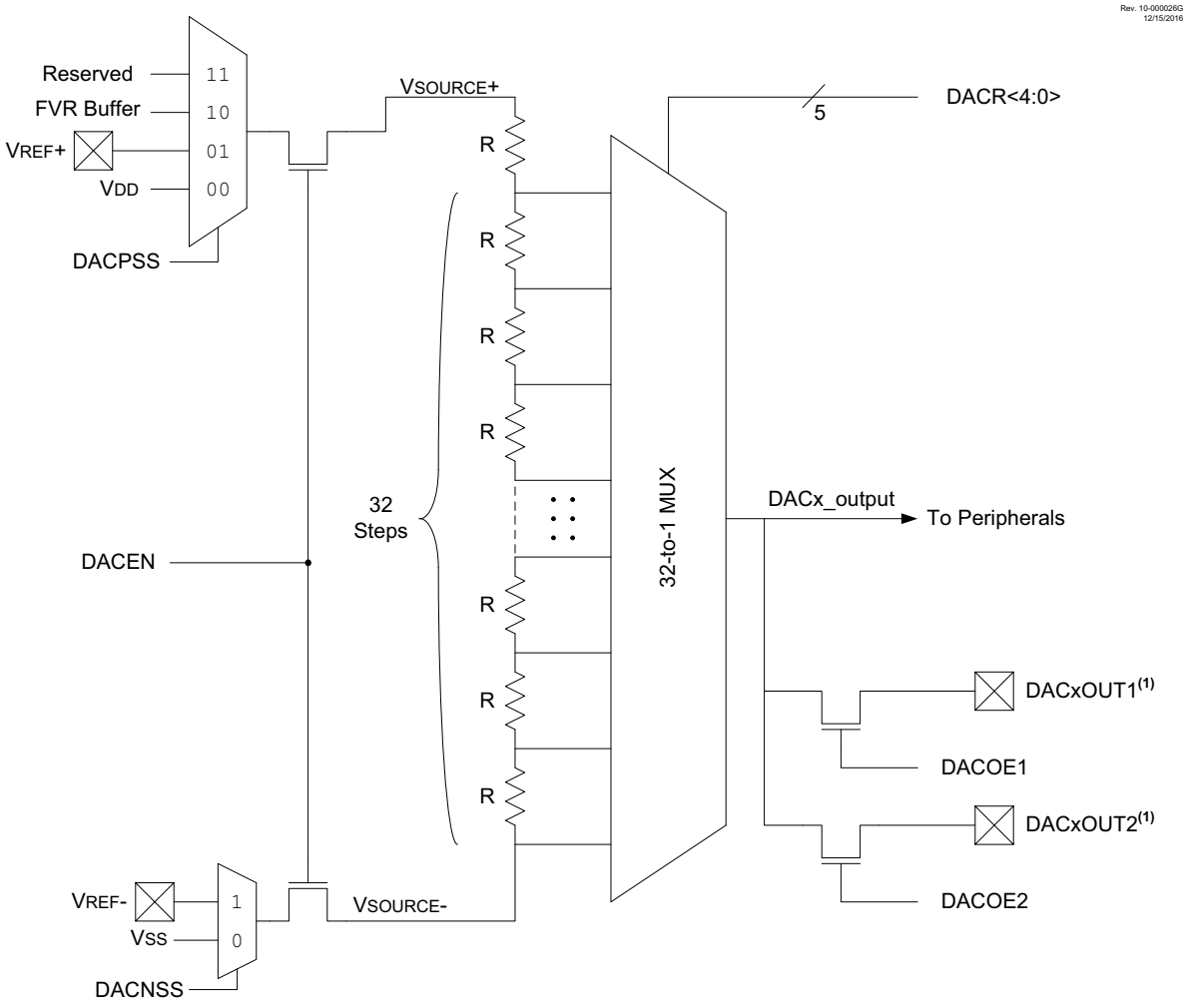
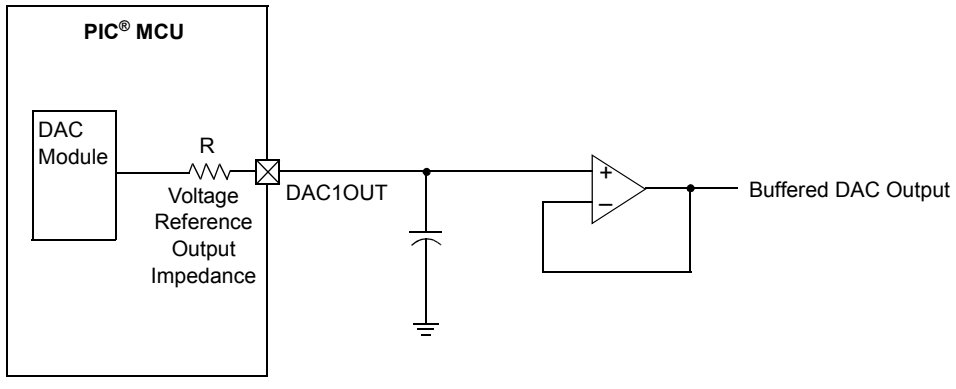


FIGURE 25-1: DIGITAL-TO-ANALOG CONVERTER BLOCK DIAGRAM



Note 1: The unbuffered DACx_output is provided on the DACxOUT pin(s).

FIGURE 25-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE



25.6 Register Definitions: DAC Control

REGISTER 25-1: DAC1CON0: VOLTAGE REFERENCE CONTROL REGISTER 0

R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0
DAC1EN	—	DAC1OE1	DAC1OE2	DAC1PSS<1:0>		—	DAC1NSS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **DAC1EN:** DAC1 Enable bit
1 = DAC is enabled
0 = DAC is disabled

bit 6 **Unimplemented:** Read as '0'

bit 5 **DAC1OE1:** DAC1 Voltage Output 1 Enable bit
1 = DAC voltage level is also an output on the DAC1OUT1 pin
0 = DAC voltage level is disconnected from the DAC1OUT1 pin

bit 4 **DAC1OE2:** DAC1 Voltage Output 1 Enable bit
1 = DAC voltage level is also an output on the DAC1OUT2 pin
0 = DAC voltage level is disconnected from the DAC1OUT2 pin

bit 3-2 **DAC1PSS<1:0>:** DAC1 Positive Source Select bits
11 = Reserved, do not use
10 = FVR output
01 = V_{REF+} pin
00 = V_{DD}

bit 1 **Unimplemented:** Read as '0'

bit 0 **DAC1NSS:** DAC1 Negative Source Select bits
1 = V_{REF-} pin
0 = V_{SS}

REGISTER 25-2: DAC1CON1: VOLTAGE REFERENCE CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	DAC1R<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **DAC1R<4:0>:** DAC1 Voltage Output Select bits
$V_{OUT} = (V_{SRC+} - V_{SRC-})*(DAC1R<4:0>/32) + V_{SRC}$

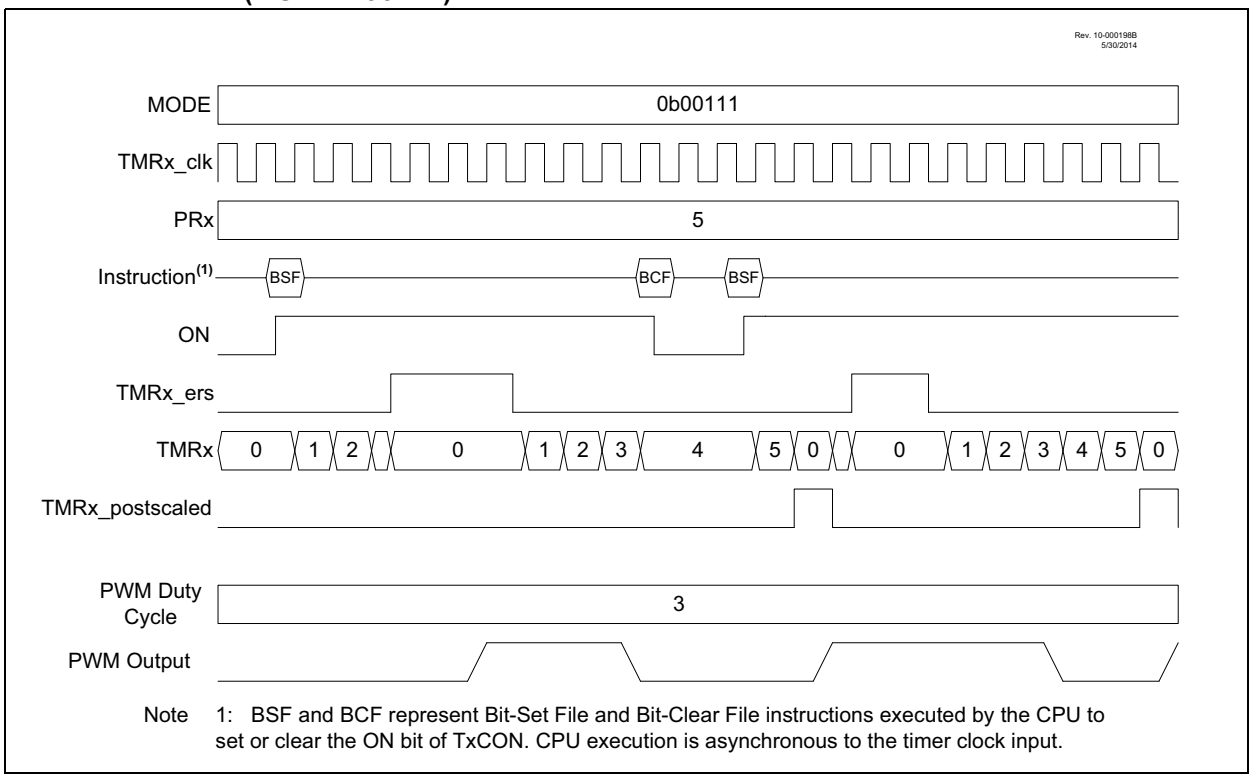
29.5.4 LEVEL-TRIGGERED HARDWARE LIMIT MODE

In the Level-Triggered Hardware Limit Timer modes the counter is reset by high or low levels of the external signal TMRx_ers, as shown in Figure 29-7. Selecting MODE<4:0> = `00110` will cause the timer to reset on a low level external signal. Selecting MODE<4:0> = `00111` will cause the timer to reset on a high level external signal. In the example, the counter is reset while TMRx_ers = `1`. ON is controlled by BSF and BCF instructions. When ON = `0` the external signal is ignored.

When the CCP uses the timer as the PWM time base then the PWM output will be set high when the timer starts counting and then set low only when the timer count matches the CCPRx value. The timer is reset when either the timer count matches the PRx value or two clock periods after the external Reset signal goes true and stays true.

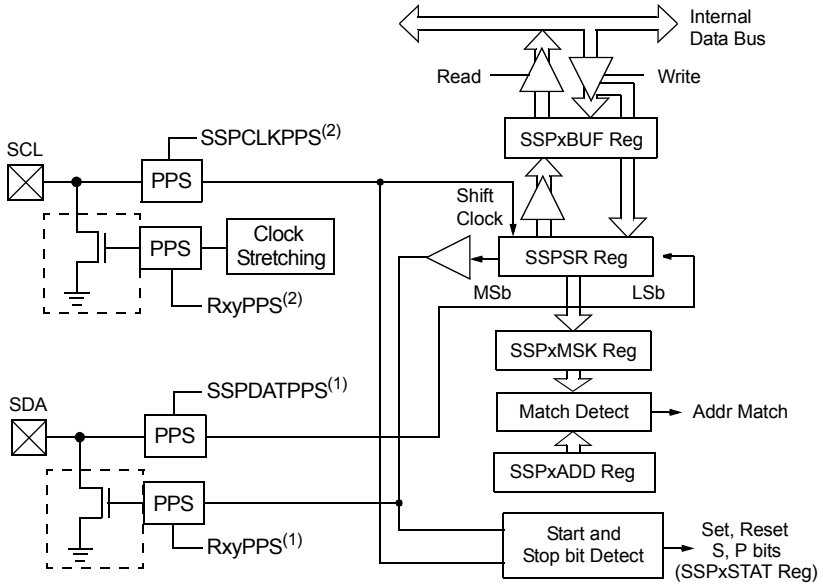
The timer starts counting, and the PWM output is set high, on either the clock following the PRx match or two clocks after the external Reset signal relinquishes the Reset. The PWM output will remain high until the timer counts up to match the CCPRx pulse width value. If the external Reset signal goes true while the PWM output is high then the PWM output will remain high until the Reset signal is released allowing the timer to count up to match the CCPRx value.

FIGURE 29-7: LEVEL-TRIGGERED HARDWARE LIMIT MODE TIMING DIAGRAM (MODE = `00111`)



Note 1: BSF and BCF represent Bit-Set File and Bit-Clear File instructions executed by the CPU to set or clear the ON bit of TxCON. CPU execution is asynchronous to the timer clock input.

FIGURE 31-3: MSSP BLOCK DIAGRAM (I^2C SLAVE MODE)



Note 1: SDA pin selections must be the same for input and output

2: SCL pin selections must be the same for input and output

31.6.13.1 Bus Collision During a Start Condition

During a Start condition, a bus collision occurs if:

a) SDA or SCL are sampled low at the beginning of the Start condition (Figure 31-33).

b) SCL is sampled low before SDA is asserted low (Figure 31-34).

During a Start condition, both the SDA and the SCL pins are monitored.

If the SDA pin is already low, or the SCL pin is already low, then all of the following occur:

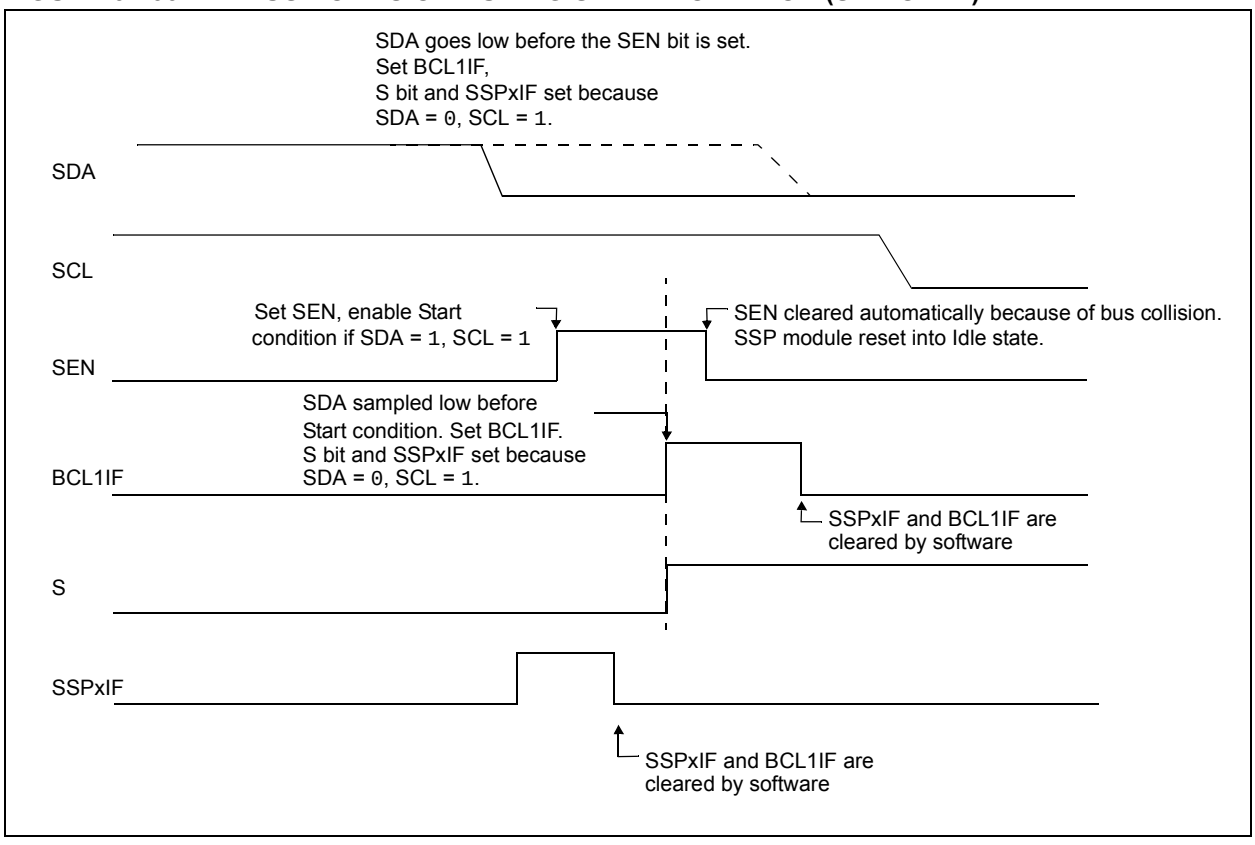
- the Start condition is aborted,
- the BCL1IF flag is set and
- the MSSP module is reset to its Idle state (Figure 31-33).

The Start condition begins with the SDA and SCL pins deasserted. When the SDA pin is sampled high, the Baud Rate Generator is loaded and counts down. If the SCL pin is sampled low while SDA is high, a bus collision occurs because it is assumed that another master is attempting to drive a data '1' during the Start condition.

If the SDA pin is sampled low during this count, the BRG is reset and the SDA line is asserted early (Figure 31-35). If, however, a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The Baud Rate Generator is then reloaded and counts down to zero; if the SCL pin is sampled as '0' during this time, a bus collision does not occur. At the end of the BRG count, the SCL pin is asserted low.

Note:	The reason that bus collision is not a factor during a Start condition is that no two bus masters can assert a Start condition at the exact same time. Therefore, one master will always assert SDA before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the Start condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start or Stop conditions.

FIGURE 31-33: BUS COLLISION DURING START CONDITION (SDA ONLY)



31.6.13.3 Bus Collision During a Stop Condition

Bus collision occurs during a Stop condition if:

a) After the SDA pin has been deasserted and allowed to float high, SDA is sampled low after the BRG has timed out (Case 1).

b) After the SCL pin is deasserted, SCL is sampled low before SDA goes high (Case 2).

The Stop condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the Baud Rate Generator is loaded with SSPxADD and counts down to zero. After the BRG times out, SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 31-38). If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 31-39).

FIGURE 31-38: BUS COLLISION DURING A STOP CONDITION (CASE 1)

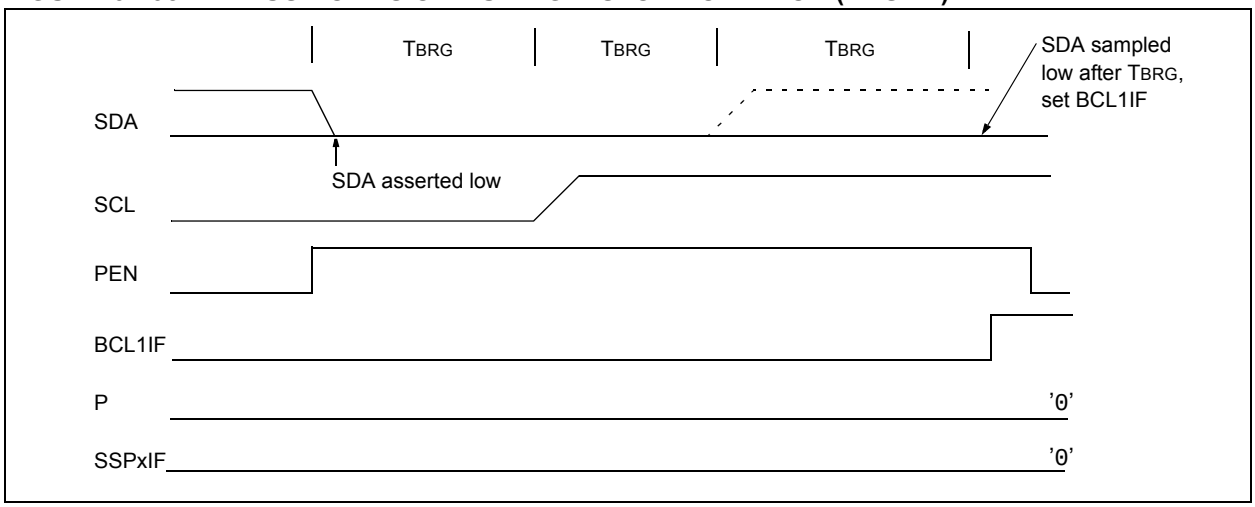


FIGURE 31-39: BUS COLLISION DURING A STOP CONDITION (CASE 2)

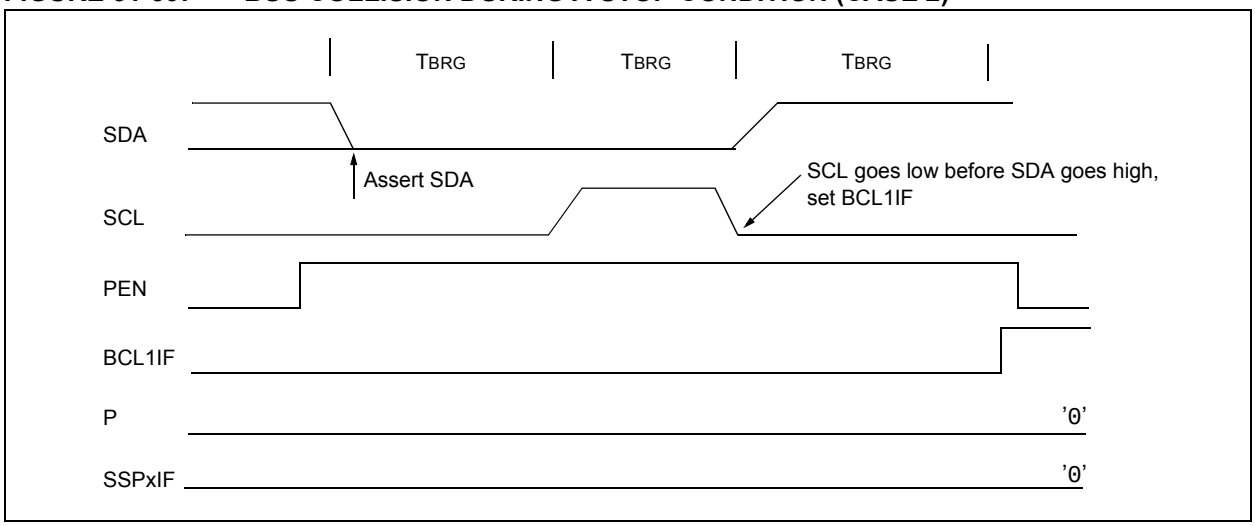


FIGURE 32-6: PERIOD AND DUTY-CYCLE REPEAT ACQUISITION MODE TIMING DIAGRAM

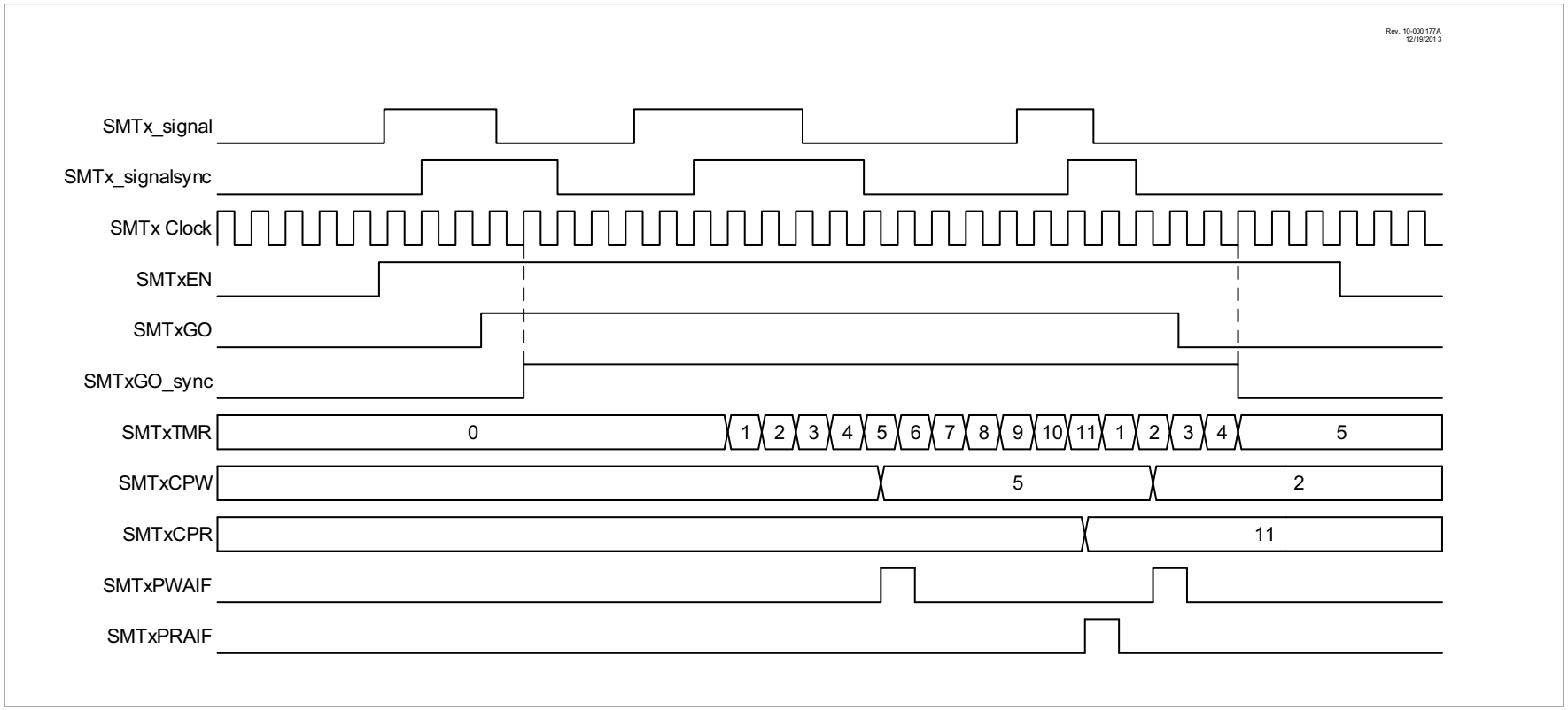
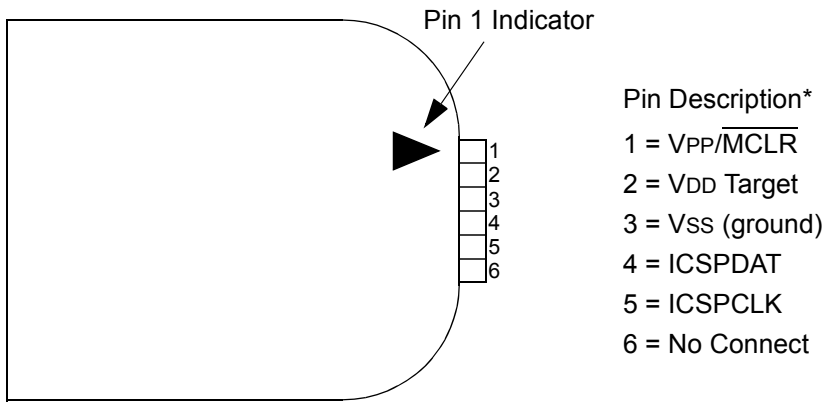
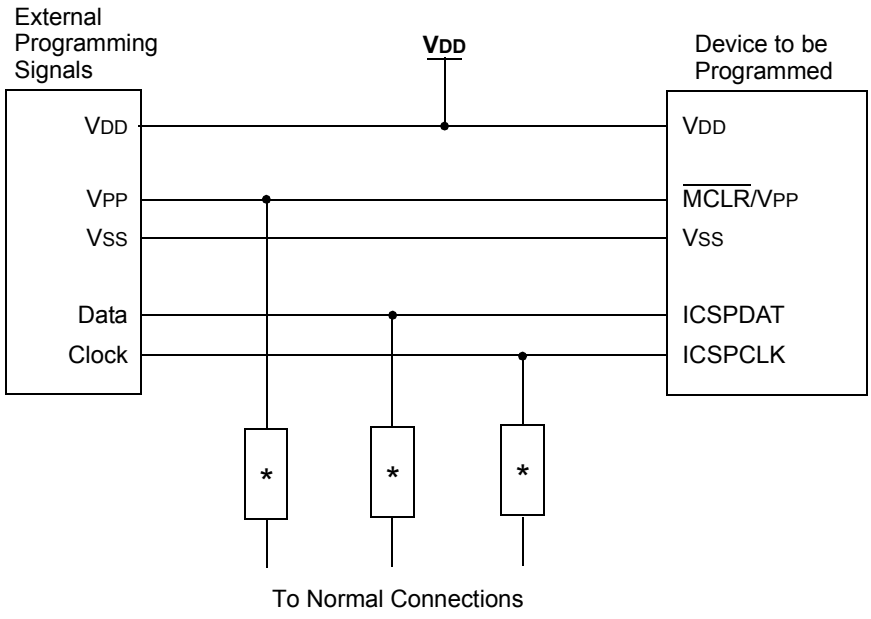


FIGURE 35-2: PICkit™ PROGRAMMER STYLE CONNECTOR INTERFACE



* The 6-pin header (0.100" spacing) accepts 0.025" square pins.

FIGURE 35-3: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



* Isolation devices (as required).

37.0 ELECTRICAL SPECIFICATIONS

37.1 Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on pins with respect to V_{SS}
- on V_{DD} pin
  - PIC16F18856/76 ..... -0.3V to +6.5V
  - PIC16LF18856/76 ..... -0.3V to +4.0V
- on $\overline{MCLR}$ pin ..... -0.3V to +9.0V
- on all other pins ..... -0.3V to (V_{DD} + 0.3V)

Maximum current
- on V_{SS} pin(1)
  - -40°C ≤ T_A ≤ +85°C ..... 350 mA
  - 85°C < T_A ≤ +125°C ..... 120 mA
- on V_{DD} pin for 28-Pin devices(1)
  - -40°C ≤ T_A ≤ +85°C ..... 250 mA
  - 85°C < T_A ≤ +125°C ..... 85 mA
- on V_{DD} pin for 40-Pin devices(1)
  - -40°C ≤ T_A ≤ +85°C ..... 350 mA
  - 85°C < T_A ≤ +125°C ..... 120 mA
- on any standard I/O pin ..... ±50 mA

Clamp current, I_K (V_{PIN} < 0 or V_{PIN} > V_{DD}) ..... ±20 mA
Total power dissipation(2) ..... 800 mW

Note 1: Maximum current rating requires even load distribution across I/O pins. Maximum current rating may be limited by the device package power dissipation characterizations, see Table 37-6 to calculate device specifications.

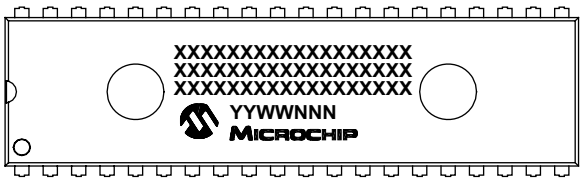
2: Power dissipation is calculated as follows:

$$P_{DIS} = V_{DD} \times \{I_{DD} - \Sigma I_{OH}\} + \Sigma \{(V_{DD} - V_{OH}) \times I_{OH}\} + \Sigma (V_{OI} \times I_{OL})$$

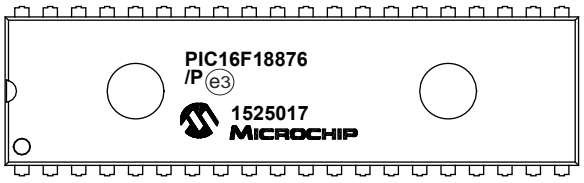
† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

40.1 Package Marking Information (Continued)

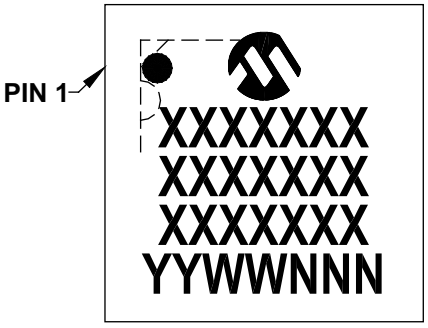
40-Lead PDIP (600 mil)



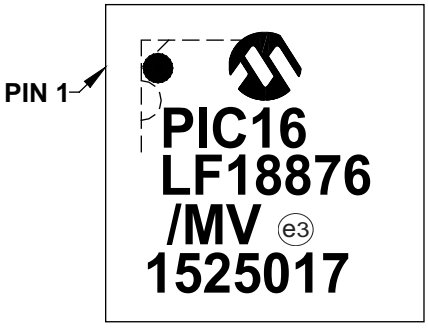
Example



40-Lead UQFN (5x5x0.5 mm)



Example

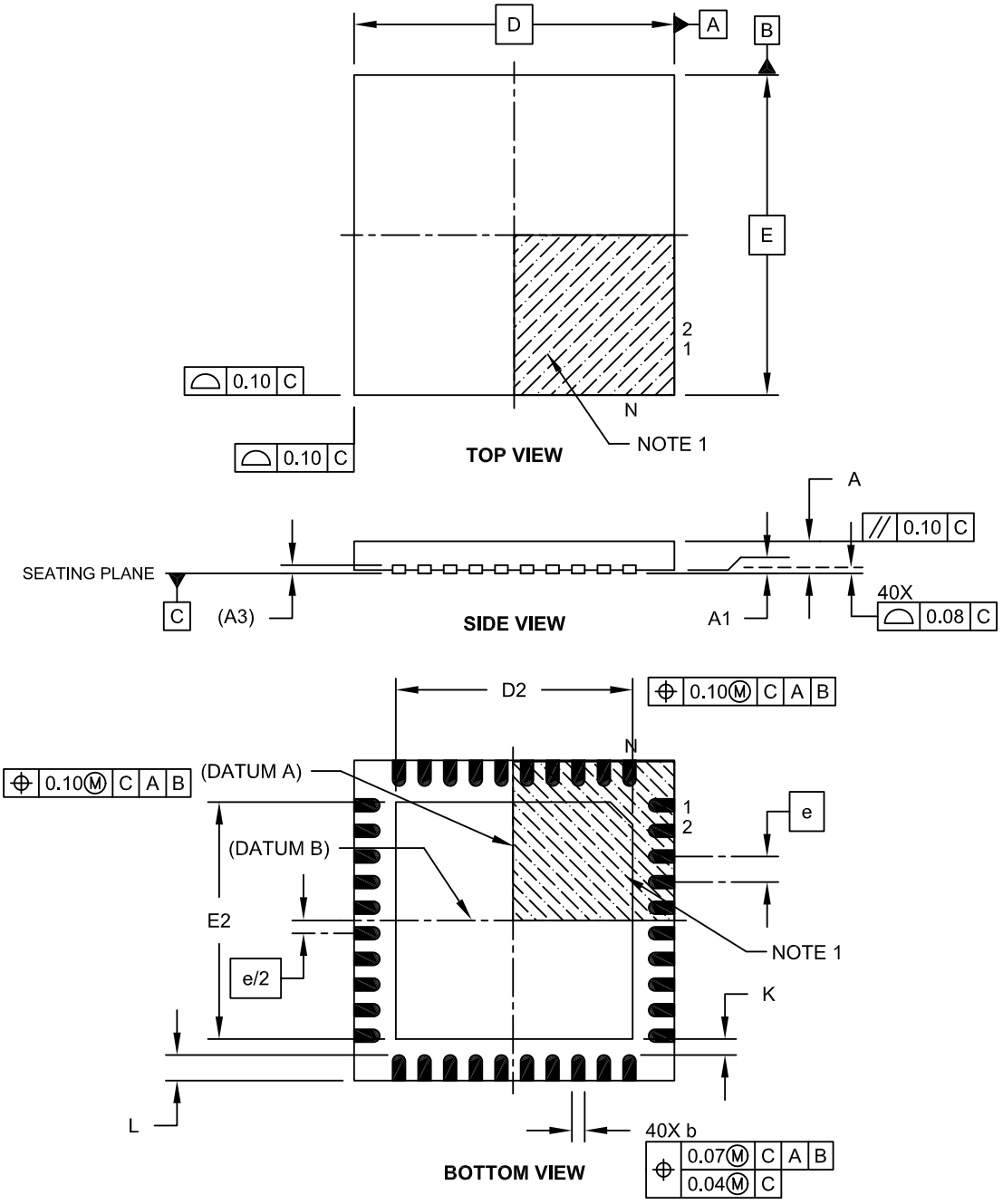


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
		Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

40-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) – 5x5x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-156A Sheet 1 of 2